

FIG. 1

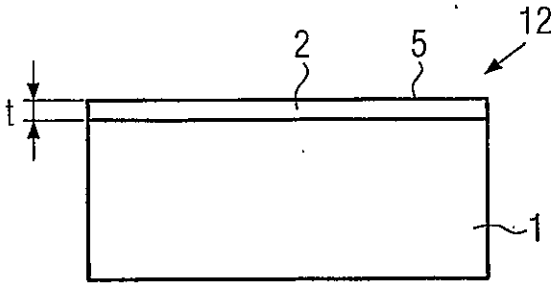


FIG. 2

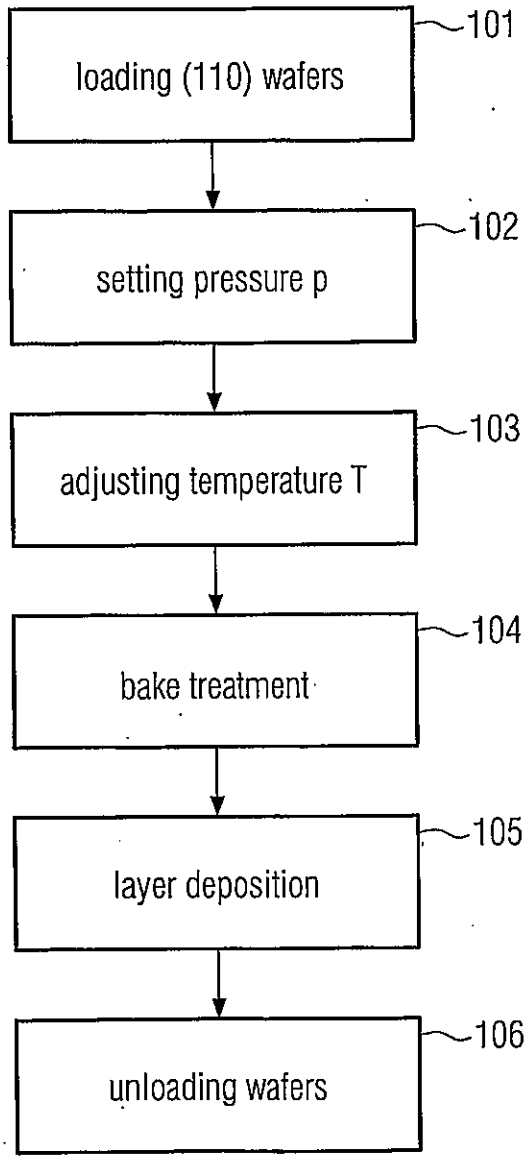

loading (110) wafers
101
setting pressure p
102
adjusting temperature T
103
bake treatment
104
layer deposition
105
unloading wafers
106

FIG. 3

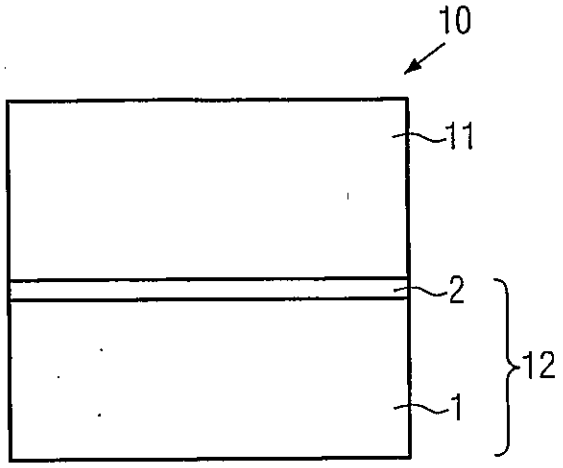


FIG. 4

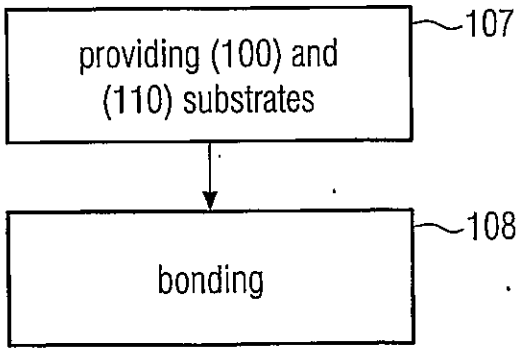


FIG. 5